IN THE CLAIMS

1. (Currently Amended) A module comprising:

a substrate with a side,

a semiconductor device,

a shield of an electrically conducting material, and

an antenna mounted on the substrate, said shield being present between the antenna and the semiconductor device,

wherein the shield and the antenna are present substantially at the same side of the substrate as the semiconductor device, **wherein the shield is connected to the antenna by a support, and wherein the support is a strip having a first end and a second end, which strip is undetachably connected at its first end to the metal plate of the antenna and is fastened at its second end to the shield**.

2. (Cancelled)

3. (Currently Amended) A module as claimed in claim 1 ~~2~~, wherein the shield and the antenna are metal plates which each comprise a first, a second, and a third portion, said second portion adjoining the first and the third portion and being oriented substantially parallel to the substrate, while at least one of said first and third portions is connected with electrical conduction to electrical conductors at one of the sides of the substrate.

4. (Previously Presented) A module as claimed in claim 3, wherein the support comprises a rubbery, electrically insulating material.

5. (Cancelled)

6. (Previously Presented) A module as claimed in claim 3, wherein the third portion of the antenna is provided with teeth which are connected to the electrical conductors at one of the sides of the substrate.

7. (Currently Amended) **A module comprising:**

a substrate with a side,

a semiconductor device,

a shield of an electrically conducting material, and

an antenna mounted on the substrate, said shield being present between the antenna and the semiconductor device,

wherein the shield and the antenna are present substantially at the same side of the substrate as the semiconductor device, wherein the shield is connected to the antenna to the antenna by a support ~~A module as claimed in claim 2,~~ wherein the support is the carrier of the antenna and comprises an electrically insulating material, the shield is a metal plate which comprises a first, a second, and a third portion, said second portion adjoining the first and the third portion and being oriented substantially parallel to the substrate, while at least one of said first and third portions are connected with electrical conduction to electrical conductors at one of the sides of the substrate, and the support is fastened on the shield.

8.(Currently Amended) **A module comprising:**

a substrat with a sid ,

a semiconductor d vic ,

a shield of an electrically conducting material, and

an antenna mounted on the substrate, said shield being present between the antenna and the semiconductor device,

wherein the shield and the antenna are present substantially at the same side of the substrate as the semiconductor device, wherein the shield is connected to the antenna to the antenna by a support and ~~A module as claimed in claim 2~~, wherein the support is the carrier of the antenna and of the shield.

9. (Previously Presented) A module as claimed in claim 8, wherein the support comprises a first, a second, and a third portion, said second portion adjoining the first and the third portion and being oriented so as to be substantially parallel to the substrate, while said first and third portions extend up to the substrate.

10. - 20. (Cancelled)

21. (New) The module of Claim 1, wherein a carrier is present on which the module and at least one component are fastened, which component emits radiation during operation of the device, the module and the component each having a height with respect to the carrier such that the height of the module is greater than the height of the component.

22. (New) The module of Claim 1, wherein at least a portion of the shield and of the antenna are exposed to air so as to provide for the removal of heat from the module.

23. (New) Th modul of Claim 1, wherein the support is connected by an electrically conductive glue.

24. (New) The module of Claim 7, wherein at least a portion of the shield and of the antenna are exposed to air so as to provide for the removal of heat from the module.

25. (New) The module of Claim 8, at least a portion of the shield and of the antenna are exposed to air so as to provide for the removal of heat from the module.